## 07-15-1998

DT-2681 RI	ECC	and alies ilis! [15]	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office					
To the Honorable Commissioner of Patents a	— 100	0765331	constrained documents or complete					
	IN TRACEIRA RS. FLE		A					
1. Name of conveying party(ies)  Byung-Bong Choi			Electronics Co., Ltd.					
Additional name(s) of conveying party(ies Yes <u>X</u> No	s) attached?	Street Address:	541, 5-Ga, Namdaemoon-Ro					
3. Nature of conveyance: MRD 6-3	3098	City:	Jung-Gu Seoul, Korea					
X Assignment Security Agreement Merger Change of Name Other		Additional name(s)	& address(es) attached? Yes X No					
Execution Date: May 28, 1998.								
4. Application number(s) or patent number(s)	:							
If this document is being filed together with a new application, the execution date of the application is: May 28, 1998.								
A. Patent Application No.(s)		B. Patent	No.(s)					
Addit:	ional numbers attac	ched? Yes _X	No					
<ol><li>Name and address of party to whom correspondence concerning document should be mailed:</li></ol>	ondence		of applications and ved1					
Name: Chai Im Internal Address: ANDERSON, KILL & OLICK, P.C Street Address: 1251 Avenue of the Americas		7. Total fee (37 CFR 3.41)						
44th Floor City: <u>NEW YORK</u> State: <u>N.Y.</u> Zip:	10020-1182	8. Deposit account number: 01-1944 .  (Attach duplicate copy of this page if paying by deposit account)						
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## ASSIGNMENT

WHEREAS, I, Byung-Bong CHOI, ASSIGNOR, a citizen of Republic of Korea, residing at Video Research Center, Daewoo Electronics Co., Ltd., 541, 5-Ga, Namdaemoon-Ro, Jung-Gu, Seoul, Korea, am the inventor of the invention in METHOD AND APPARATUS FOR RECOVERING DIGITAL DATA BY EMPLOYING ASYNCHRONOUS DATA SAMPLING TECHNIQUE for which I have executed an application for a Patent of the United States								
Ø	which is executed on	×	even date herewith or		(date)			

and WHEREAS, Daewoo Electronics Co., Ltd., 541, 5-Ga, Namdaemoon-Ro, Jung-Gu, Seoul, Korea, ASSIGNEE is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application:

which is identified by Anderson Kill & Olick, P.C. docket no. \_\_\_\_\_\_.

which was filed on \_\_\_\_\_, Serial No. \_\_\_\_\_

NOW. THEREFORE, in consideration of the sum of One Dollar (US\$1.00) to me in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I, the said ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND I HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, I hereunto set my hand and seal the day and year set opposite my signature.

Date	May 18	. 1998	Choi	Band.	Bony	I S
Daic						